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ABSTRACT

ELECTRONIC CIRCUIT INTERCONNECTION SYSTEM USING
VIRTUAL MIRROR PACKAGES

A package (e.g., a “chip carrier”) (301) containing an integrated or other electronic circuit includes connection points (e.g., pins or solder pads) (302, 303) arranged in a virtual mirror pattern. Pairs of electrically interconnected connection points are arranged such that one connection point of each pair is positioned adjacent one edge (301a) of the chip carrier, and the corresponding connection point of each pair is located adjacent another edge (301b) of the chip carrier. In a computer or other information processing system having a bus comprised of a multiplicity of parallel conductors (304) on one surface of a substrate (e.g., a printed circuit board), several virtual mirror packages can be connected to that bus such that the space between adjacent packages is arbitrarily small. The close proximity of the packages significantly reduces the signal propagation delay time and permits higher speed operation of the bus.



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Fig. 3